

*Technical Bulletin***“SUPER-LOW TEMP”**
LEAD-FREE WIRE SOLDER*Description*

Super-Low Temp. Wire Solder is designed for use when soldering to surfaces where excess heat or higher temperature solder alloys could disrupt the base material or previously soldered joints in adjacent areas.

Super-Low Temp. Wire Solder is made of a Lead-Free alloy consisting of 42% Tin and 58% Bismuth. This alloy is eutectic with both solidus and liquidus at 281F. A eutectic alloy is preferable for soldering operations to reduce the chance of joint fracture from movement during cooling.

ASTM B774

Tin	41.5-42.5%
Bismuth	57.5-58.5%
Lead	0.050% max.
Cadmium	0.005% max.
Copper	0.080% max.
Antimony	0.100% max.
Zinc	0.080% max.
Silver	0.010% max.
All Others	0.080% max.

Physical Data

Solidus	281 F
Liquidus	281 F

Sizes Available

0.030" / 0.062" / 0.125"
diameter solid wire;
4.5 lb Ingots